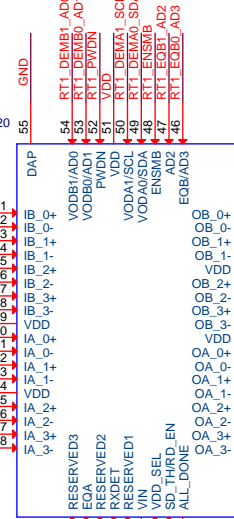
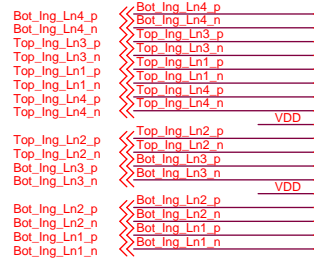
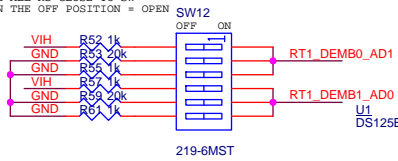


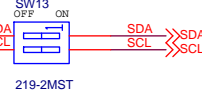
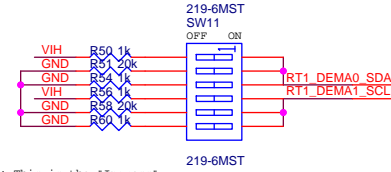
Ingress Datapath

REFERENCE DESIGN NOTE: DIP Switches are not necessary if DS125BR820 device configuration is to be performed via I2C/SMBus or pin strapping.

PLACE ALL R_s CLOSE TO SW
SW IN THE OFF POSITION = OPEN

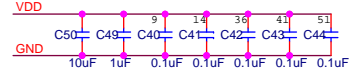
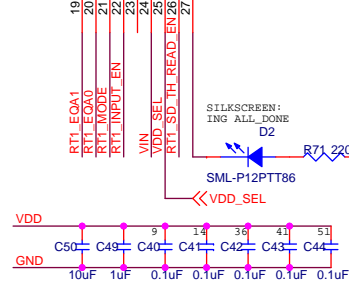
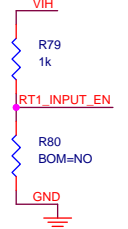
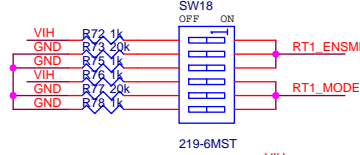
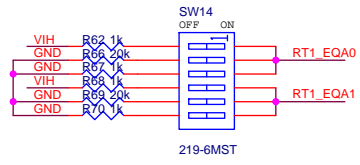
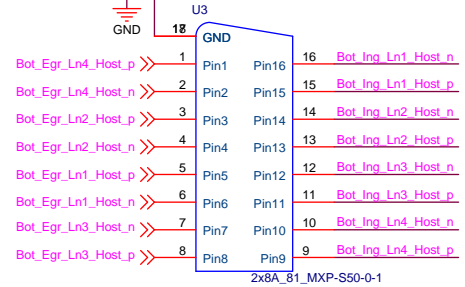


LAYOUT NOTE: This is the "Ingress" DS125BR820, and it is placed on the top of the board. It can be further away from the QSPF+ if needed.

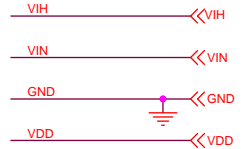


REFERENCE DESIGN NOTE: This high-speed connector is not needed if signals are routed to Switch ASIC.

LAYOUT NOTE: This connector is placed on the top of the board, the same side as the Ingress DS100KR800, and it should be placed as close to the DS100KR800 as possible.



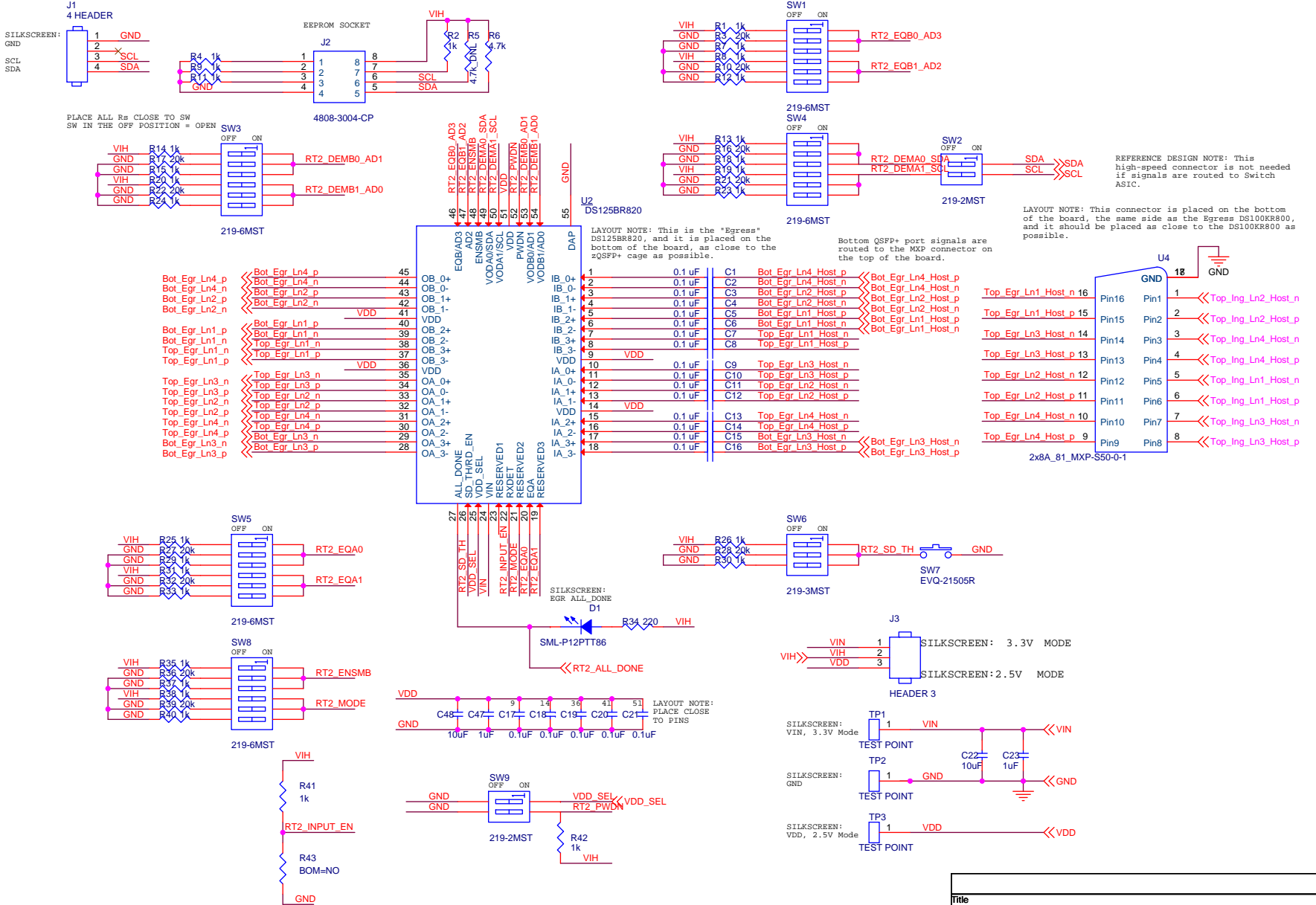
LAYOUT NOTE: PLACE CLOSE TO PINS



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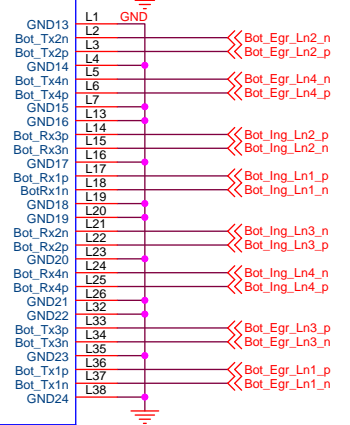
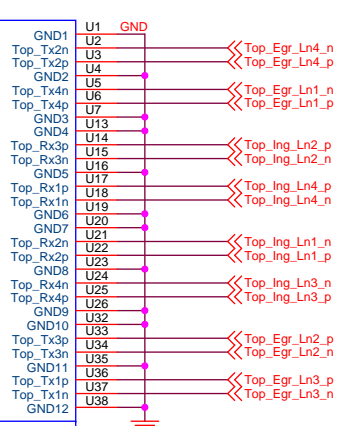
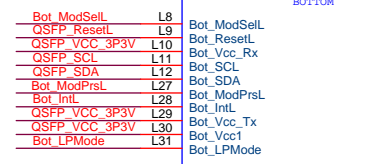
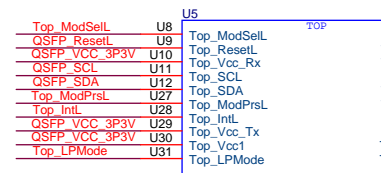
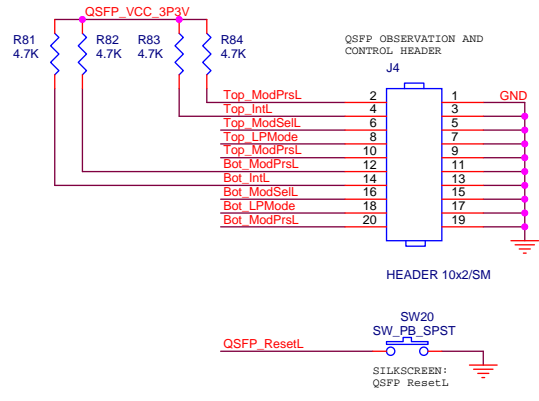
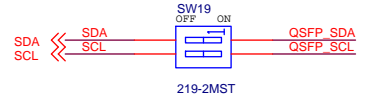
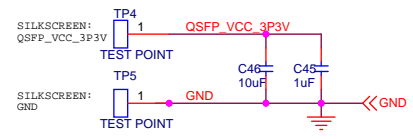
Egress Datapath

REFERENCE DESIGN NOTE: DIP Switches are not necessary if DS125BR820 device configuration is to be performed via I2C/SMBus or pin strapping.



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zQSFP+



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